

省电型流控螺线管驱动器

查询样品: [DRV120](#)

特性

- 用于控制螺线管电流的带有脉宽调制 (PWM) 的集成金属氧化物半导体场效应晶体管 (MOSFET)
 - 用于调节螺线管电流的外部感测电阻器
- 螺线管电流的快速斜升以保证激活
- 在保持模式中, 为了实现低功耗和热耗散, 螺线管电流被减少
- 可外部设定峰值电流、峰值电流的保持时间、保持电流和 PWM 时钟频率。它们还可以在无需外部组件的情况下在标称值上运行。
- 内部电源电压调节
 - 高达 28V 的外部电源电压
- 保护
 - 热关断
 - 欠压闭锁 (UVLO)
 - 最大斜升时间
 - 可选状态 (STATUS) 输出
- 运行温度范围: -40°C 至 105°C
- 8 引脚和 14 引脚 薄型小外形尺寸 (TSSOP) 封装选项

应用范围

- 电动机械驱动器: 螺线管、阀门、继电器
- 大型家用电器、太阳能、运输

说明

DRV120 是一款针对螺线管的 PWM 电流驱动器。它被设计成使用控制良好的电流来调节电流以确保激活并同时减少功率耗散。螺线管电流快速斜升以确保阀门或者继电器的打开。在最初的斜升后, 螺线管电流被保持在峰值以确保正确运行, 这之后, 为了避免过热问题并减少功率耗散, 这个电流被减少至较低的保持水平。

使用一个外部电容器对峰值电流的持续时间进行设定。电流斜波峰值和保持电平、以及 PWM 频率可由外部电阻器独立设定。如果针对相应参数的默认值适用于应用的话, 外部设置电阻器也可被省略。

DRV120 可由 6V 至 28V 的外部电源供电运行。

ORDERING INFORMATION⁽¹⁾

PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
(TSSOP-8) - PW	Reel of 2000	DRV120PWR	120
(TSSOP-14) - PW	Reel of 2000	DRV120APWR	120A

(1) For the most current packaging and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



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TYPICAL APPLICATION

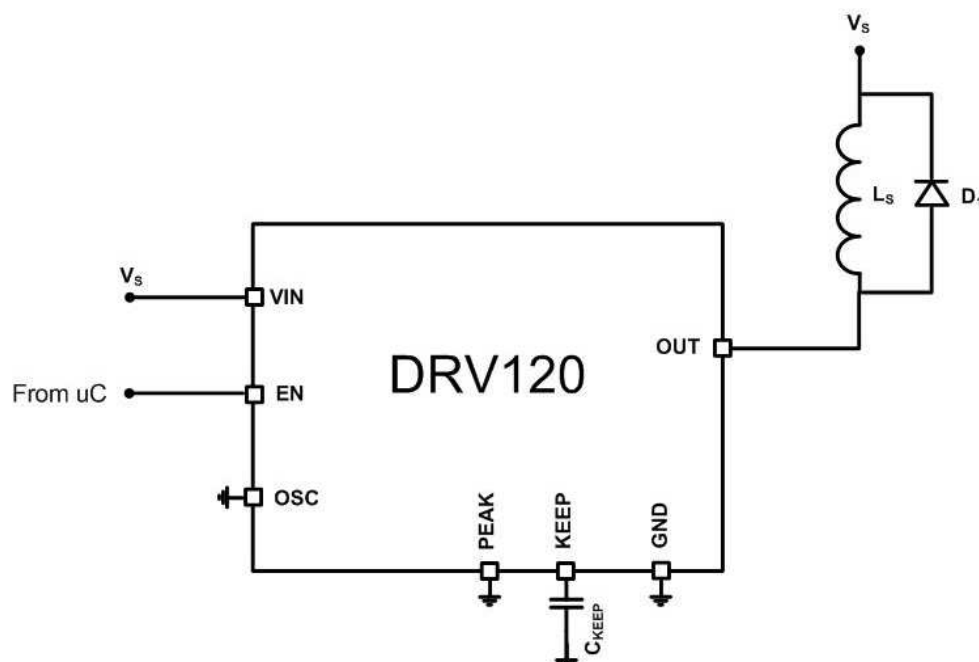


Figure 1. Default Configuration With 8-Pin TSSOP Option

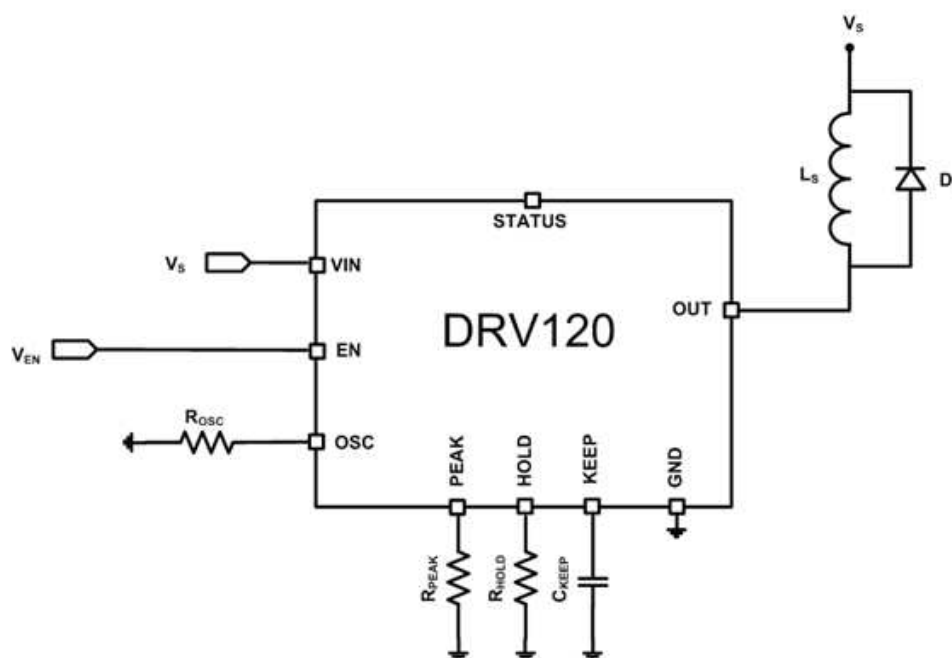


Figure 2. External Parameter Setting for 14-Pin TSSOP Option

DEVICE INFORMATION

Functional Block Diagram

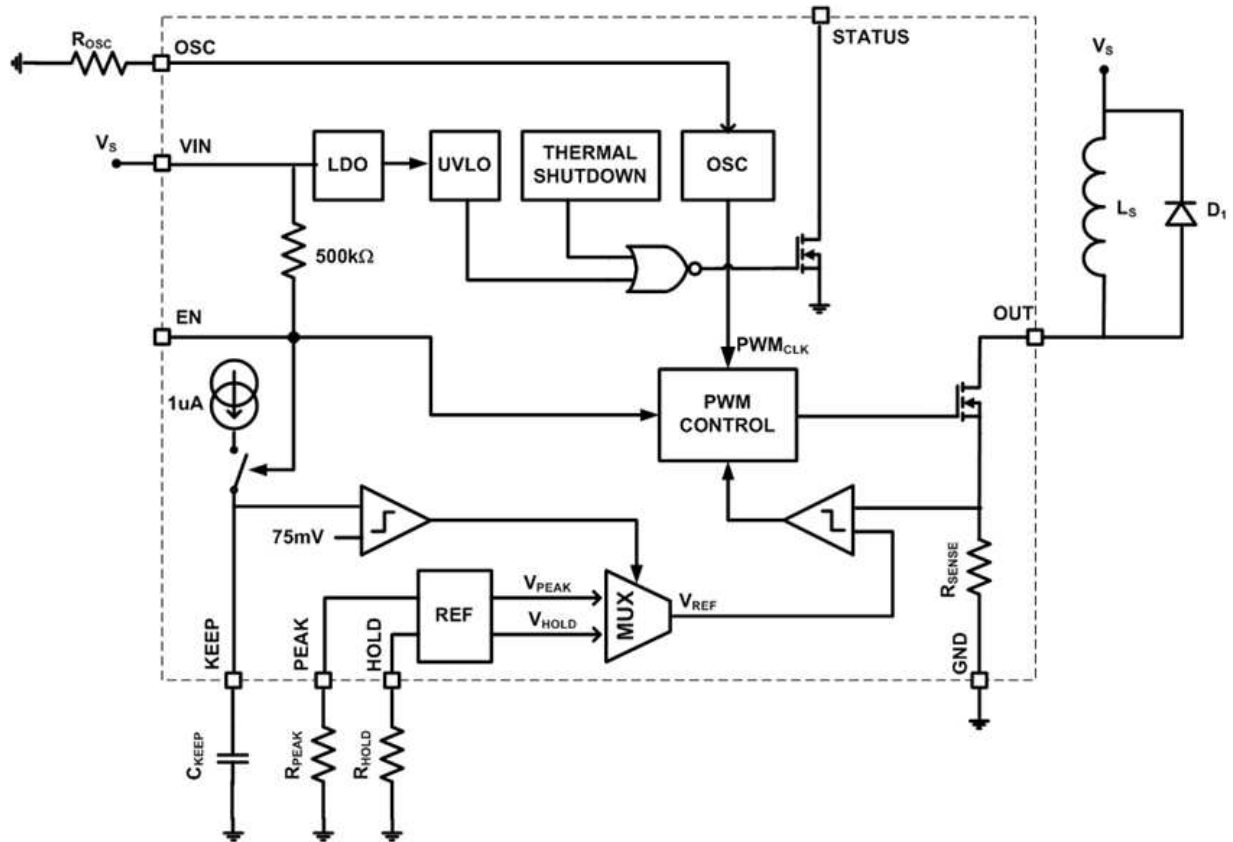
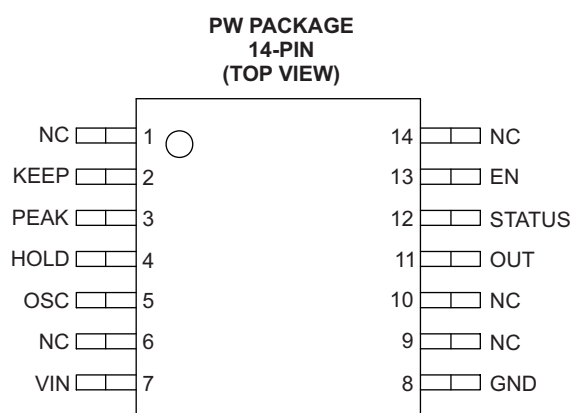
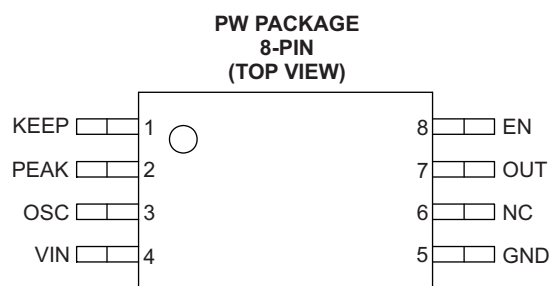


Table 1. TERMINAL FUNCTIONS

NAME	PIN (8-PIN PW) ⁽¹⁾	PIN (14-PIN PW)	DESCRIPTION
NC	6	1, 6, 9, 10, 14	No connect
KEEP	1	2	Keep time set
PEAK	2	3	Peak current set
HOLD	-	4	Hold current set
OSC	3	5	PWM frequency set
VIN	4	7	6-V to 28-V supply
GND	5	8	Ground
OUT	7	11	Controlled current sink
STATUS	-	12	Open drain fault indicator
EN	8	13	Enable

(1) In the 8-pin package, the HOLD pin is not bonded out. For this package, the HOLD mode is configured to default (internal) settings.



ABSOLUTE MAXIMUM RATINGS⁽¹⁾⁽²⁾

		VALUE	UNIT
V _{IN}	Input voltage range	–0.3 to 28	V
Voltage range on EN, STATUS, PEAK, HOLD, OSC, SENSE, RAMP		–0.3 to 7	V
Voltage range on OUT		–0.3 to 28	V
ESD rating	HBM (human body model)	2000	V
	CDM (charged device model)	500	
T _J	Operating virtual junction temperature range	–40 to 125	°C
T _{stg}	Storage temperature range	–65 to 150	°C

- Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute–maximum–rated conditions for extended periods may affect device reliability.
- All voltage values are with respect to network ground terminal.

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
I _{OUT}	Average solenoid DC current			125	mA
V _{IN}	Supply voltage	6	12	26	V
C _{IN}	Input capacitor	1	4.7		μF
L	Solenoid inductance		1		H
T _A	Operating ambient temperature	–40		105	°C

THERMAL INFORMATION

THERMAL METRIC		DRV120	DRV120	UNITS
		PW	PW	
		8 PINS	14 PINS	
θ _{JA}	Junction-to-ambient thermal resistance ⁽¹⁾	183.8	122.6	°C/W
θ _{JCTop}	Junction-to-case (top) thermal resistance ⁽²⁾	69.2	51.2	
θ _{JB}	Junction-to-board thermal resistance ⁽³⁾	112.6	64.3	
ψ _{JT}	Junction-to-top characterization parameter ⁽⁴⁾	10.4	6.5	
ψ _{JB}	Junction-to-board characterization parameter ⁽⁵⁾	110.9	63.7	
θ _{JCbot}	Junction-to-case (bottom) thermal resistance ⁽⁶⁾	N/A	N/A	

- 在 JESD51-2a 描述的环境中，按照 JESD51-7 的指定，在一个 JEDEC 标准高 K 电路板上进行仿真，从而获得自然 对流条件下的结至环境热阻。
- 通过在封装顶部模拟一个冷板测试来获得结至芯片外壳（顶部）的热阻。不存在特定的 JEDEC 标准测试，但 可在 ANSI SEMI 标准 G30-88 中找到内容接近的说明。
- 按照 JESD51-8 中的说明，通过 在配有用于控制 PCB 温度的环形冷板夹具的环境中进行仿真，以获得结板热阻。
- 结至顶部特征参数， ψ_{JT}，估算真实系统中器件的结温，并使用 JESD51-2a（第 6 章和第 7 章）中 描述的程序从仿真数据中 提取出该参数以便获得 θ_{JA}。
- 结至电路板特征参数， ψ_{JB}，估算真实系统中器件的结温，并使用 JESD51-2a（第 6 章和第 7 章）中 描述的程序从仿真数据中 提取出该参数以便获得 θ_{JA}。
- 通过在外露（电源）焊盘上进行冷板测试仿真来获得 结至芯片外壳（底部）热阻。不存在特定的 JEDEC 标准 测试，但可在 ANSI SEMI 标准 G30-88 中找到内容接近的说明。

ELECTRICAL CHARACTERISTICS

$V_{IN} = 14\text{ V}$, $T_A = -40^\circ\text{C}$ to 105°C , over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SUPPLY						
I _Q	Standby current	EN = 0, V _{IN} = 14 V		100	150	μA
	Quiescent current	EN = 1, V _{IN} = 14 V		300	400	
CURRENT DRIVER						
R _{OUT}	OUT to GND resistance	I _{OUT} = 200 mA		1.7	2.5	Ω
f _{PWM}	PWM frequency	OSC = GND	15	20	25	kHz
D _{MAX}	Maximum PWM duty cycle			100		%
D _{MIN}	Minimum PWM duty cycle			9		%
t _D	Start-up delay	Delay between EN going high until driver enabled ⁽¹⁾ , f _{PWM} = 20 kHz		25	50	μs
CURRENT CONTROLLER, INTERNAL SETTINGS						
I _{PEAK}	Peak current	PEAK = GND	160	200	240	mA
I _{HOLD}	Hold current	HOLD = GND	40	50	60	mA
CURRENT CONTROLLER, EXTERNAL SETTINGS						
t _{KEEP} ⁽²⁾	Externally set keep time at peak current	C _{KEEP} = 1 μF		75		ms
I _{PEAK}	Externally set peak current	R _{PEAK} = 50 kΩ		250		mA
		R _{PEAK} = 200 kΩ		83		
I _{HOLD}	Externally set hold current	R _{HOLD} = 50 kΩ		100		mA
		R _{HOLD} = 200 kΩ		33		
f _{PWM}	Externally set PWM frequency	R _{OSC} = 50 kΩ		60		kHz
		R _{OSC} = 200 kΩ		20		
LOGIC INPUT LEVELS (EN)						
V _{IL}	Input low level				1.3	V
V _{IH}	Input high level		1.65			V
R _{EN}	Input pull-up resistance		350	500		kΩ
LOGIC OUTPUT LEVELS (STATUS)						
V _{OL}	Output low level	Pull-down activated, I _{STATUS} = 2 mA			0.3	V
I _{IL}	Output leakage current	Pull-down deactivated, V(STATUS) = 5 V			1	μA
UNDERVOLTAGE LOCKOUT						
V _{UVLO}	Undervoltage lockout threshold			4.6		V
THERMAL SHUTDOWN						
T _{TSD}	Junction temperature shutdown threshold			160		°C
T _{TSU}	Junction temperature startup threshold			140		°C

(1) Logic HIGH between 4 V and 7 V. Note: absolute max voltage rating is 7 V.

(2) Either internal or external t_{KEEP} time setting is selected to be activated during manufacturing of production version of DRV120.

FUNCTIONAL DESCRIPTION

DRV120 controls the current through the solenoid as shown in [Figure 3](#). Activation starts when EN pin voltage is pulled high either by an external driver or internal pull-up. In the beginning of activation, DRV120 allows the load current to ramp up to the peak value I_{PEAK} and it regulates it at the peak value for the time, t_{KEEP} , before reducing it to I_{HOLD} . The load current is regulated at the hold value as long as the EN pin is kept high. The initial current ramp-up time depends on the inductance and resistance of the solenoid. Once EN pin is driven to GND, DRV120 allows the solenoid current to decay to zero.

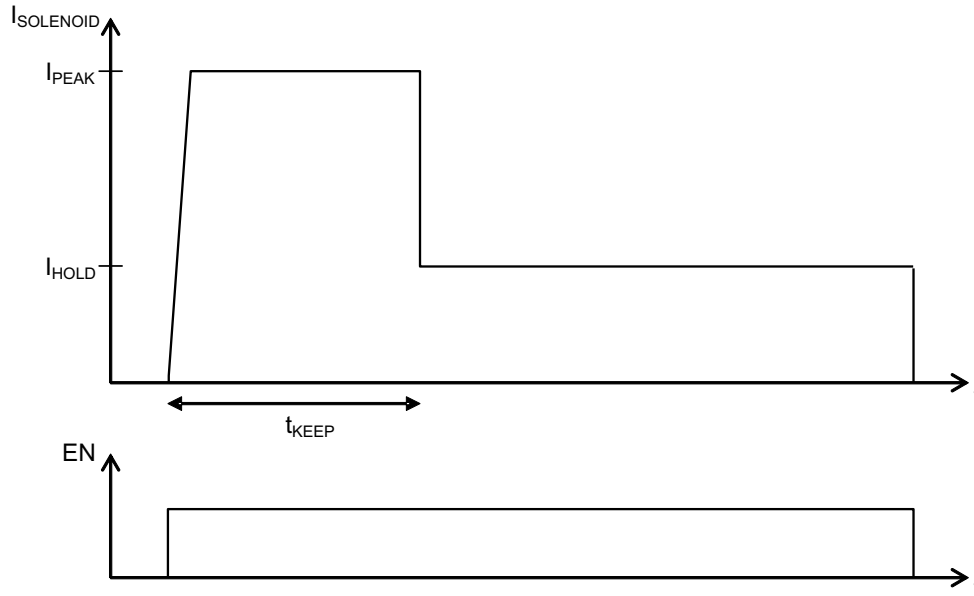


Figure 3. Typical Current Waveform Through the Solenoid

t_{KEEP} is set externally by connecting a capacitor to the KEEP pin. A constant current is sourced from the KEEP pin that is driven into an external capacitor resulting in a linear voltage ramp. When the KEEP pin voltage reaches 75 mV, the current regulation reference voltage, V_{REF} , is switched from V_{PEAK} to V_{HOLD} . Dependency of t_{KEEP} from the external capacitor size can be calculated by:

$$t_{KEEP} [s] = C_{KEEP} [F] \cdot 75 \cdot 10^3 \left[\frac{s}{F} \right] \quad (1)$$

The current control loop regulates, cycle-by-cycle, the solenoid current by using an internal current sensing resistor and MOSFET switch. During the ON-cycle, current flows from OUT pin to GND pin through the internal switch as long as voltage over current sensing resistor is less than V_{REF} . As soon as the current sensing voltage is above V_{REF} , the internal switch is immediately turned off until the next ON-cycle is triggered by the internal PWM clock signal. In the beginning of each ON-cycle, the internal switch is turned on and stays on for at least the time determined by the minimum PWM signal duty cycle, D_{MIN} .

I_{PEAK} and I_{HOLD} depend on fixed resistance values R_{PEAK} and R_{HOLD} as shown in [Figure 4](#). If the PEAK pin is connected to ground or if R_{PEAK} is below 33.33 kΩ (typ value), then I_{PEAK} is at its default value (internal setting). The I_{PEAK} value can alternatively be set by connecting an external resistor to ground from the PEAK pin. For example, if a 50-kΩ ($= R_{PEAK}$) resistor is connected between PEAK and GND, then the externally set I_{PEAK} level will be 250 mA. If $R_{PEAK} = 200$ kΩ is, then the externally set I_{PEAK} level will be 83 mA. HOLD current external setting, I_{HOLD} , works in the same way, but current levels are 40% of the I_{PEAK} . External settings for I_{PEAK} and I_{HOLD} are independent of each other. I_{PEAK} and I_{HOLD} values can be calculated by using the formula below.

$$I_{PEAK} = \frac{250mA}{R_{PEAK}} \cdot 66.67k\Omega; 66.67k\Omega < R_{PEAK} < 550k\Omega \quad (2)$$

$$I_{HOLD} = \frac{100mA}{R_{HOLD}} \cdot 66.67k\Omega; 66.67k\Omega < R_{HOLD} < 250k\Omega \quad (3)$$

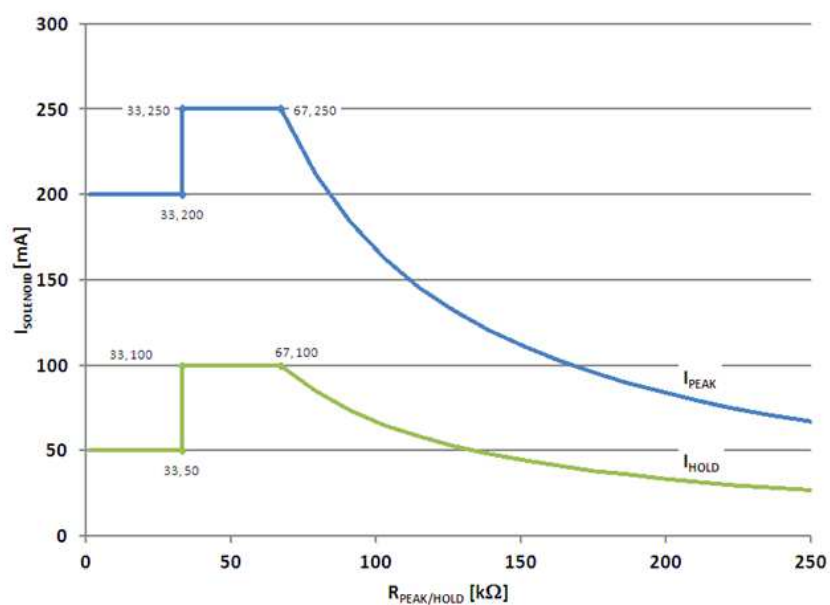


Figure 4. PEAK and HOLD Mode Current Settings

Frequency of the internal PWM clock signal, PWM_{CLK} , that triggers each ON-cycle can be adjusted by external resistor, R_{OSC} , connected between OSC and GND. Frequency as a function of resistor value is shown in Figure 5. Default frequency is used when OSC is connected to GND directly. PWM frequency as a function of external fixed adjustment resistor value (greater than 66.67 k Ω) is given below.

$$f_{PWM} = \frac{60kHz}{R_{OSC}} \cdot 66.67k\Omega; 66.67k\Omega < R_{OSC} < 2M\Omega \quad (4)$$

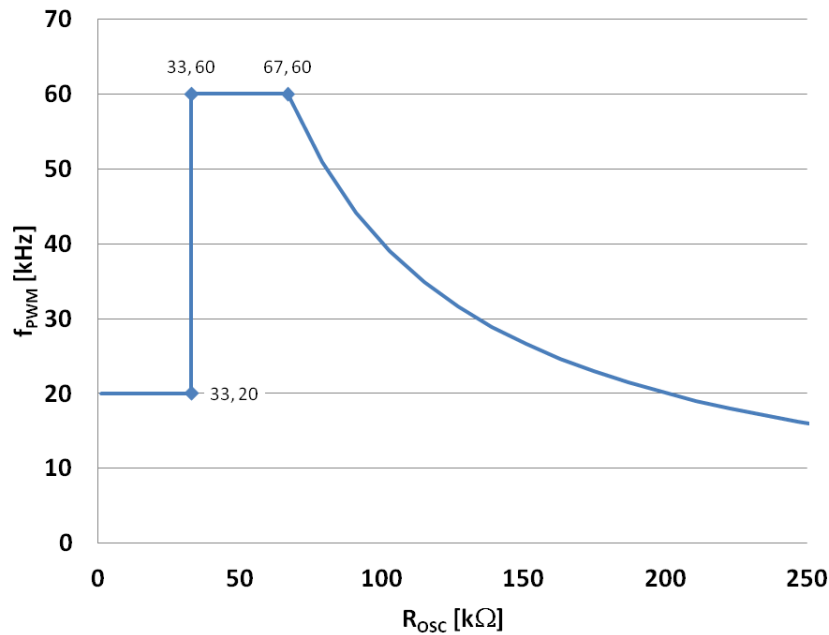


Figure 5. PWM Clock Frequency Setting

Open-drain STATUS output is deactivated if either under voltage lockout or thermal shutdown blocks have triggered.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
DRV120APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 105	120A	Samples
DRV120PWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 105	120	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

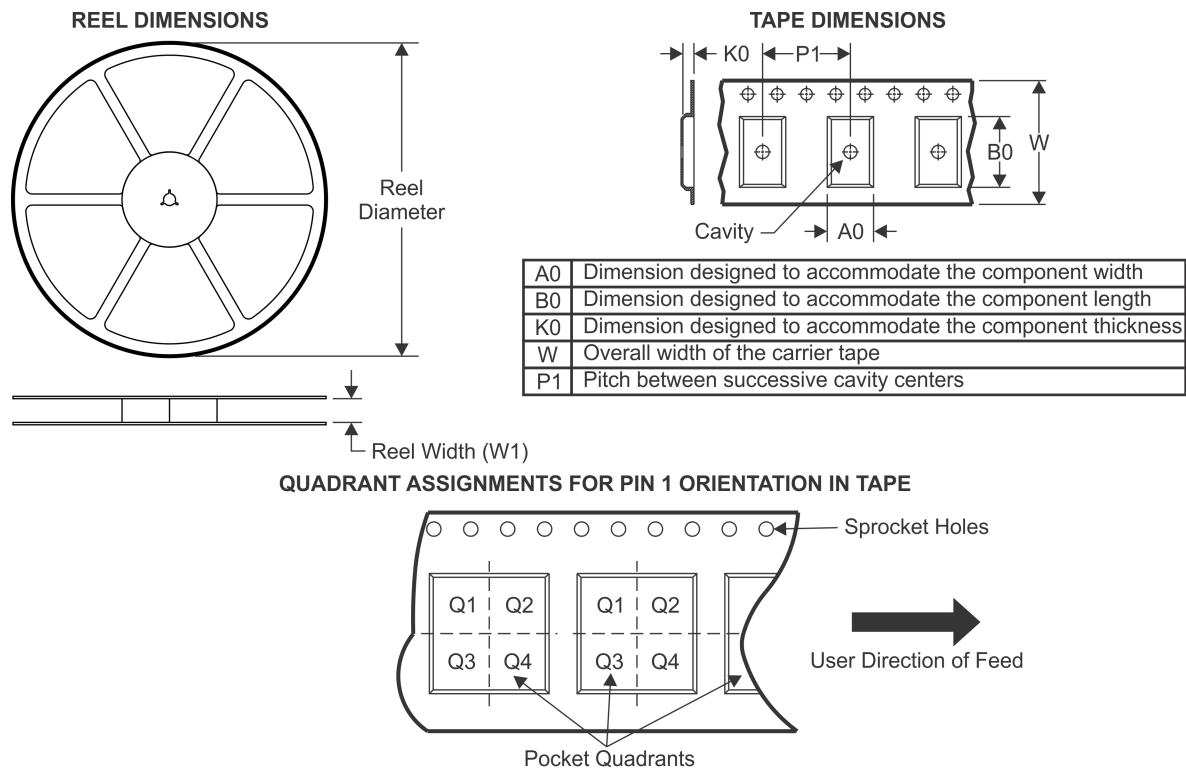
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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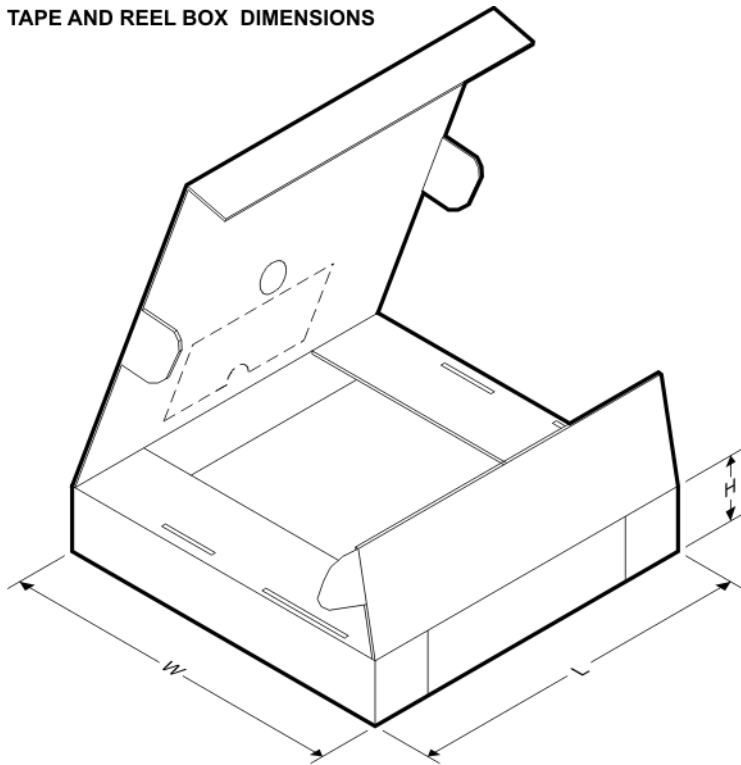
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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DRV120APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
DRV120PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

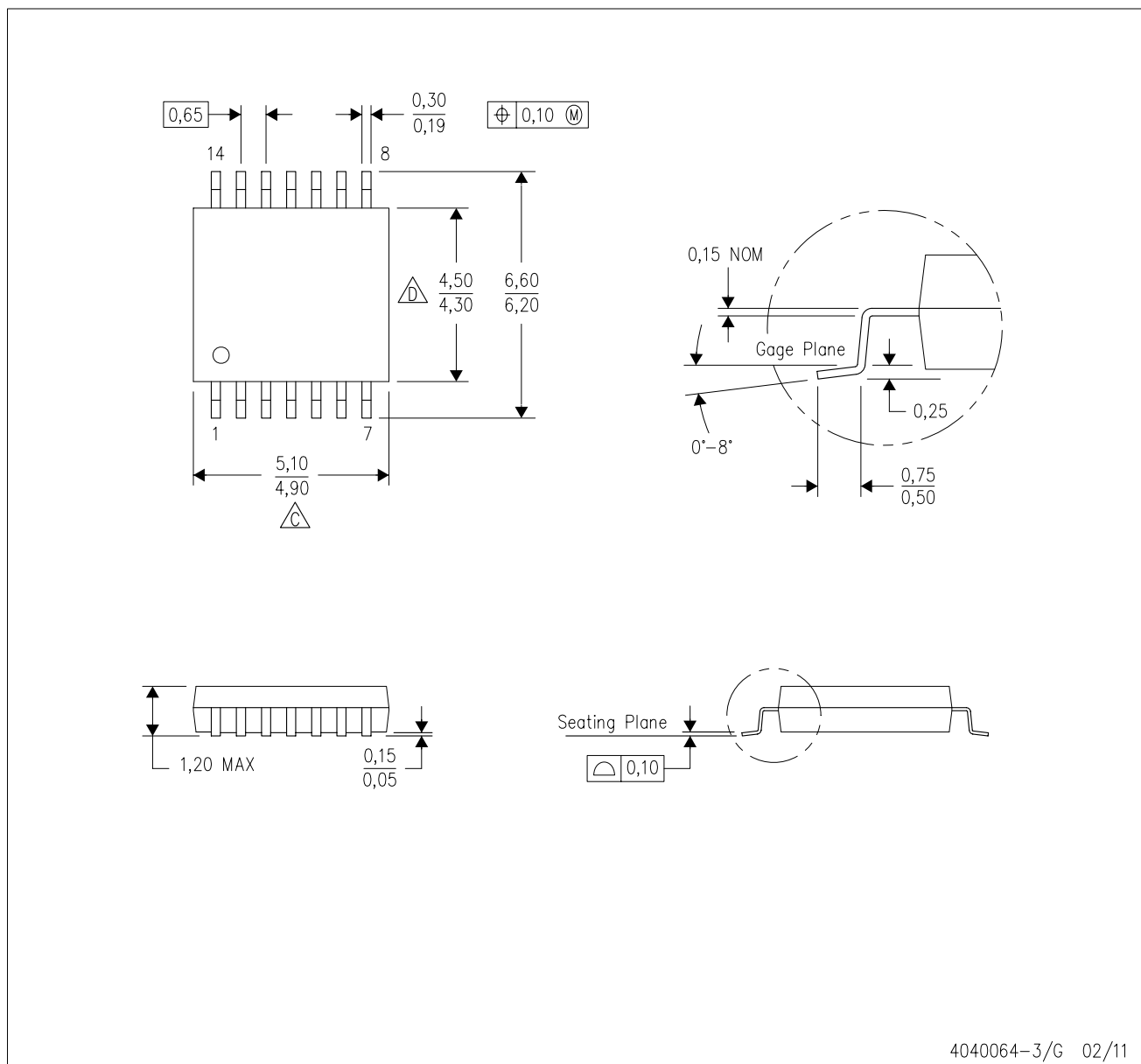


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DRV120APWR	TSSOP	PW	14	2000	367.0	367.0	35.0
DRV120PWR	TSSOP	PW	8	2000	367.0	367.0	35.0

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

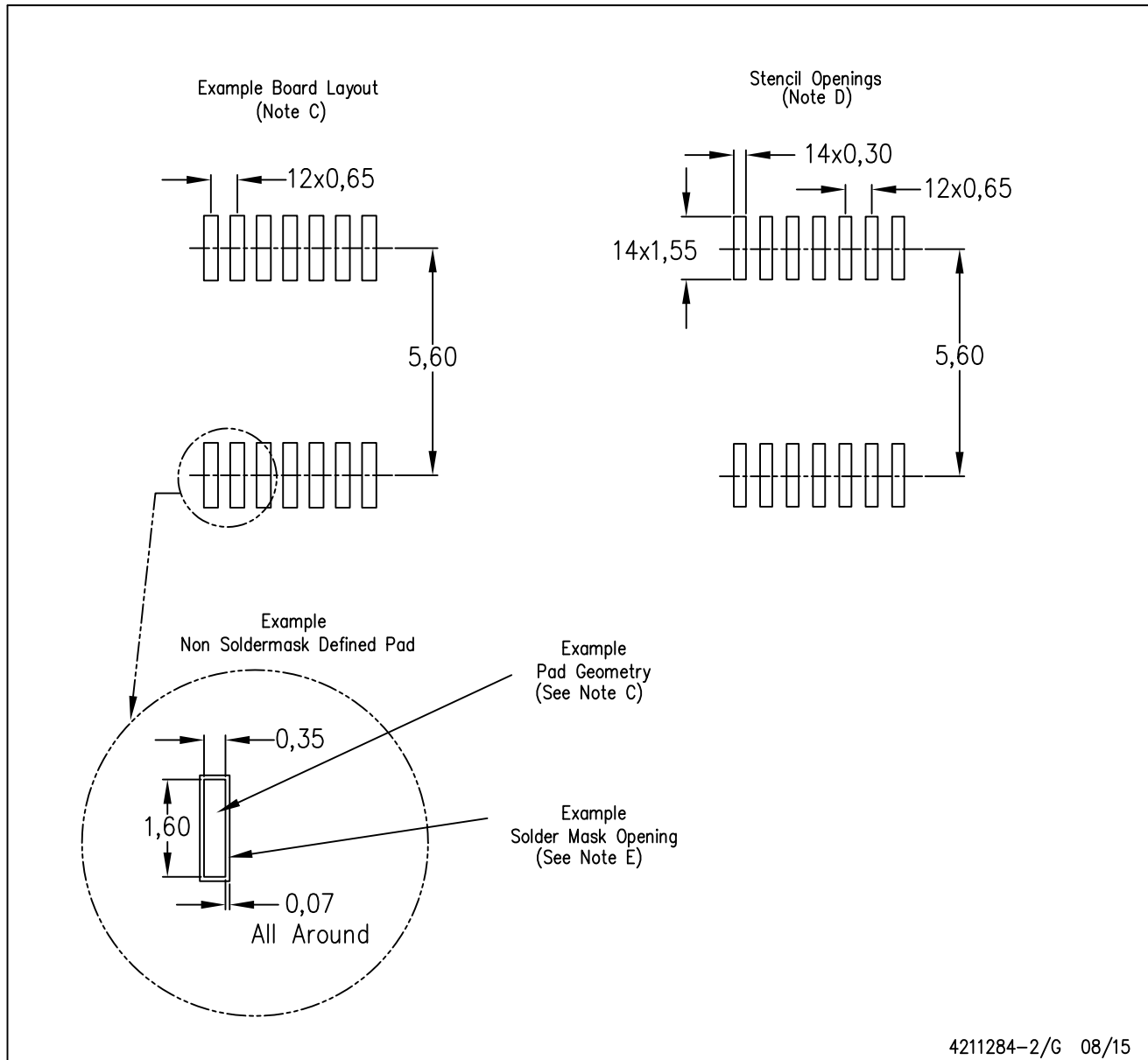


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- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

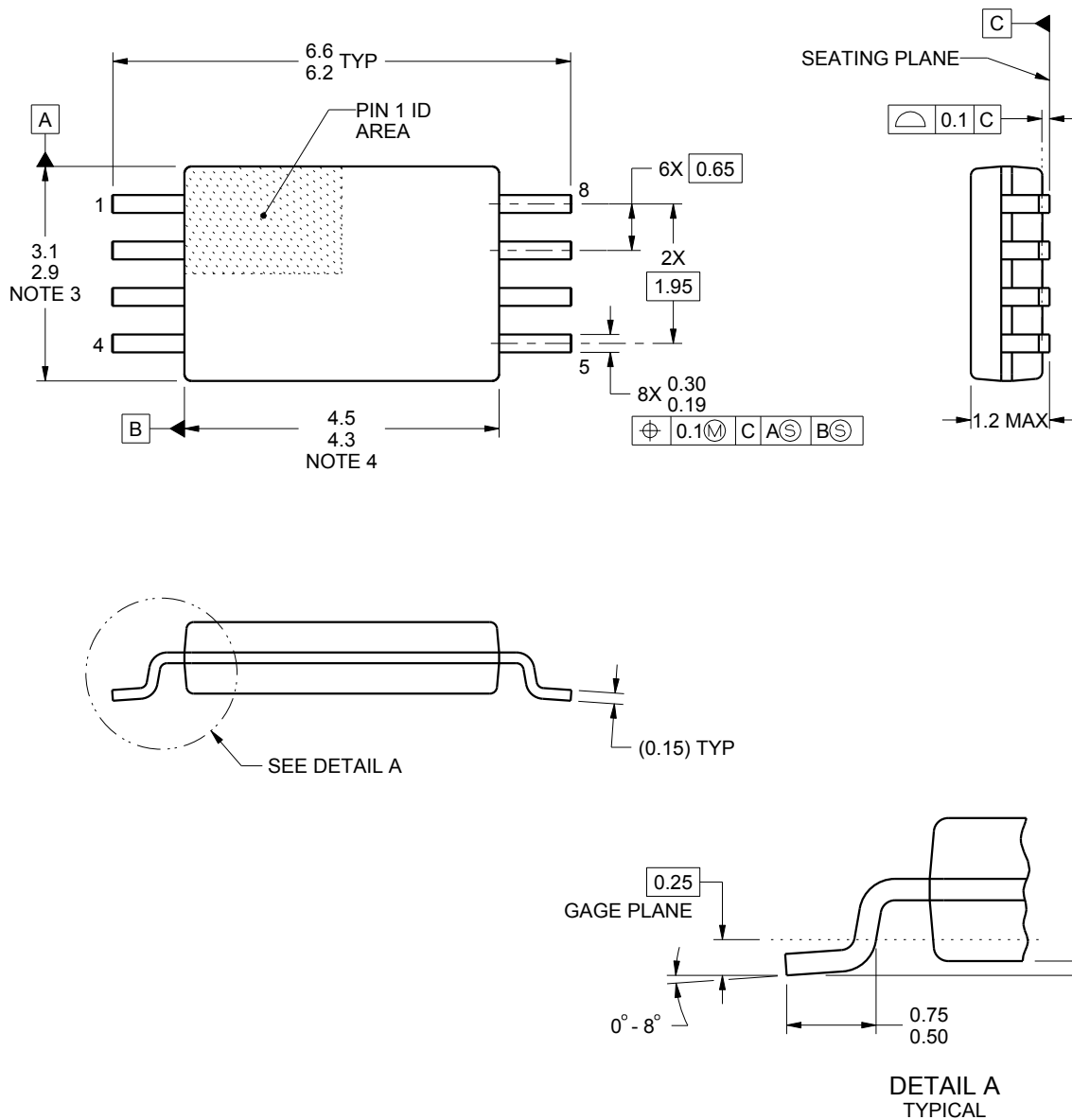
PW0008A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



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NOTES:

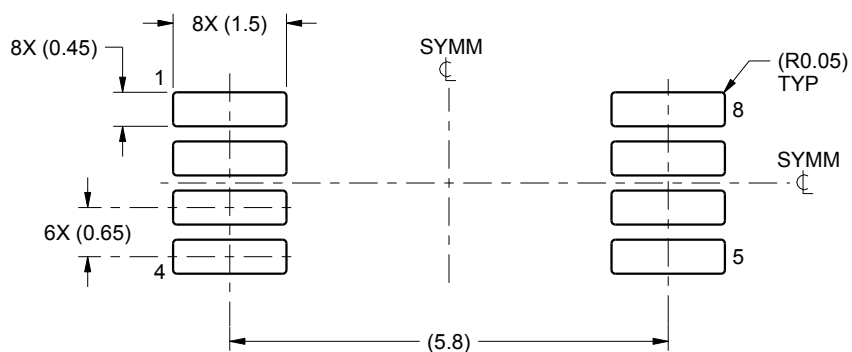
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.

EXAMPLE BOARD LAYOUT

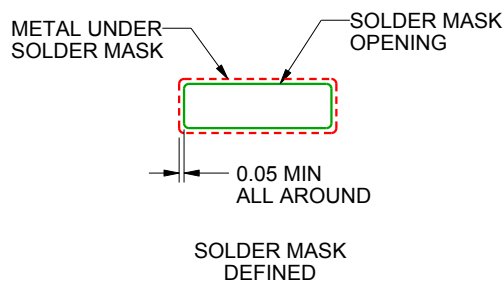
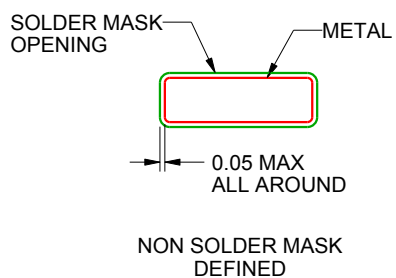
PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

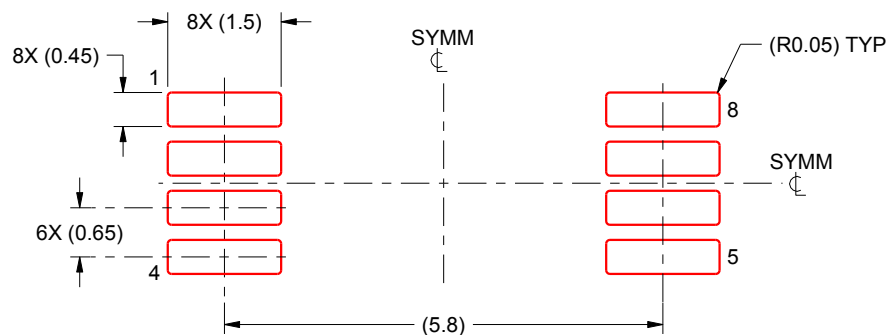
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要声明

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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